

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC014N04LS	**Issued**	4. July 2019
MA#	MA003227234		
Package	PG-TDSON-8-48	**Weight***	108.52 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.009	0.93	0.93	9301	9301
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		132	
	non noble metal	zinc	7440-66-6	0.057	0.05		528	
	non noble metal	iron	7439-89-6	1.145	1.06		10552	
	non noble metal	copper	7440-50-8	46.496	42.84	43.96	428454	439666
wire	noble metal	gold	7440-57-5	0.041	0.04	0.04	379	379
encapsulation	organic material	carbon black	1333-86-4	0.083	0.08		769	
	plastics	epoxy resin	-	3.838	3.54		35370	
	inorganic material	silicondioxide	60676-86-0	37.800	34.83	38.45	348320	384459
leadfinish	non noble metal	tin	7440-31-5	1.264	1.16	1.16	11645	11645
plating	noble metal	silver	7440-22-4	0.029	0.03	0.03	267	267
solder	noble metal	silver	7440-22-4	0.036	0.03		328	
	non noble metal	tin	7440-31-5	0.071	0.07		655	
	non noble metal	lead	7439-92-1	1.316	1.21	1.31	12126	13109
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005	0.00		42	
	non noble metal	zinc	7440-66-6	0.018	0.02		169	
	non noble metal	iron	7439-89-6	0.368	0.34		3388	
	non noble metal	copper	7440-50-8	14.930	13.76	14.12	137575	141174
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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